SUBMINIATURE SOLID STATE LAMP

Part Number: KM-27ZGC-E-09 Green

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Subminiature package.
- Z-Bend lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

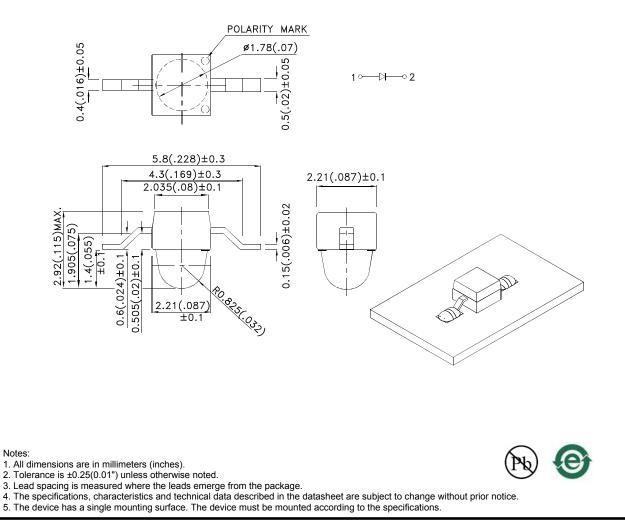
The Green source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



SPEC NO: DSAK6982 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: SEP/02/2010 DRAWN: Y.H.Wu PAGE: 1 OF 5 ERP: 1202002537

Selection Guide									
Part No.	Dice	Lens Type	lv (mo @ 20	· • •	Viewing Angle [1]				
			Min.	Тур.	201/2				
KM-27ZGC-E-09	Green (InGaN)	Water Clear	3500	4500	20°				

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	525		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	35		nm	I⊧=20mA
С	Capacitance	Green	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	4	V	I⊧=20mA
lr	Reverse Current	Green		50	uA	VR = 5V

Notes:

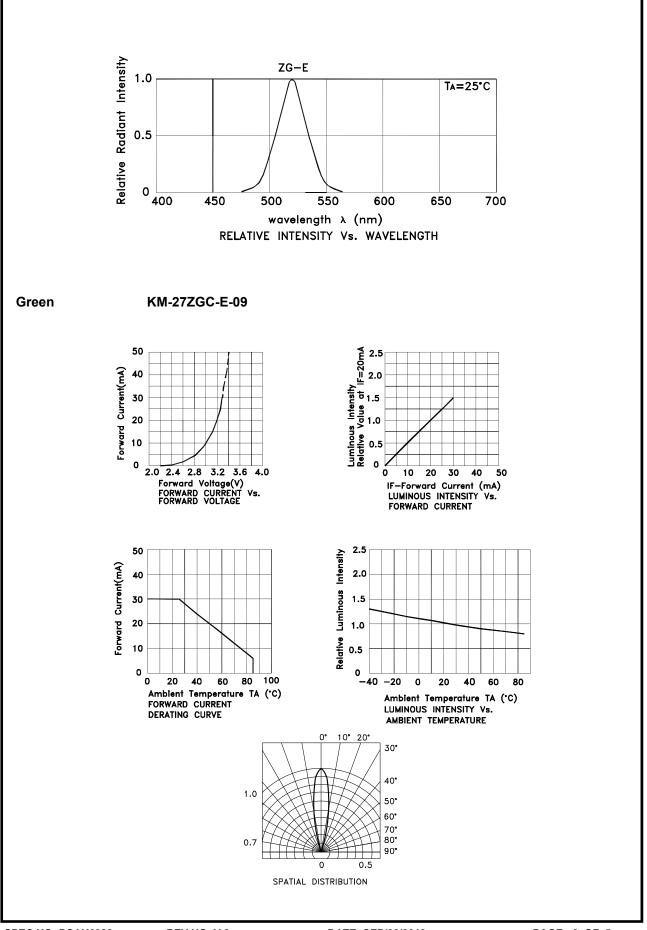
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units		
Power dissipation	120	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	100	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

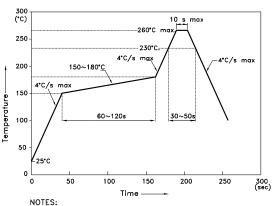
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



KM-27ZGC-E-09

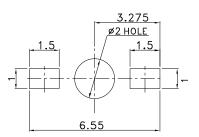
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

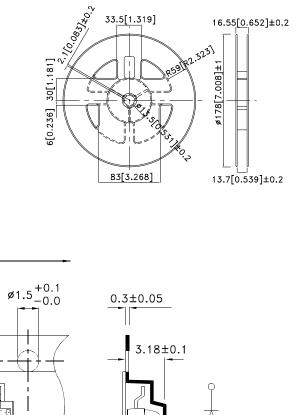


NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

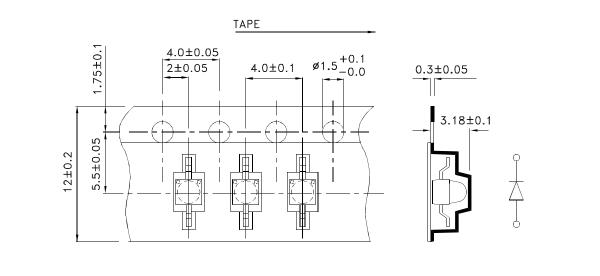
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)



REV NO: V.2 **CHECKED: Allen Liu** DATE: SEP/02/2010 DRAWN: Y.H.Wu

PAGE: 4 OF 5 ERP: 1202002537

